



STD30NF03L STD30NF03L-1

N-channel 30V - 0.020Ω - 30A - DPAK/IPAK
STripFET™ II Power MOSFET

General features

| Type | V _{DSS} | R _{DS(on)} | I _D |
|--------------|------------------|---------------------|----------------|
| STD30NF03L-1 | 30V | < 0.025Ω | 30A |
| STD30NF03L | 30V | < 0.025Ω | 30A |

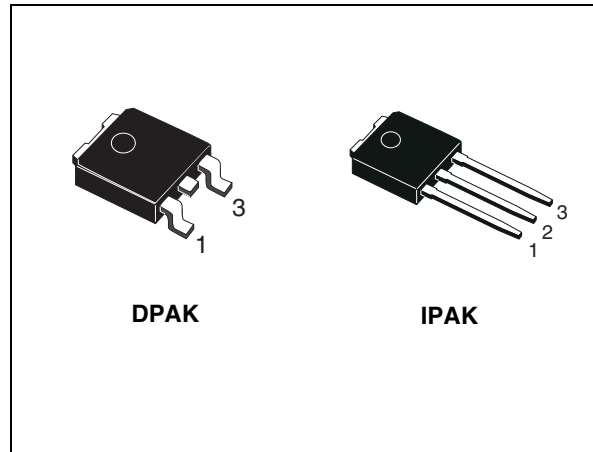
- Low threshold drive

Description

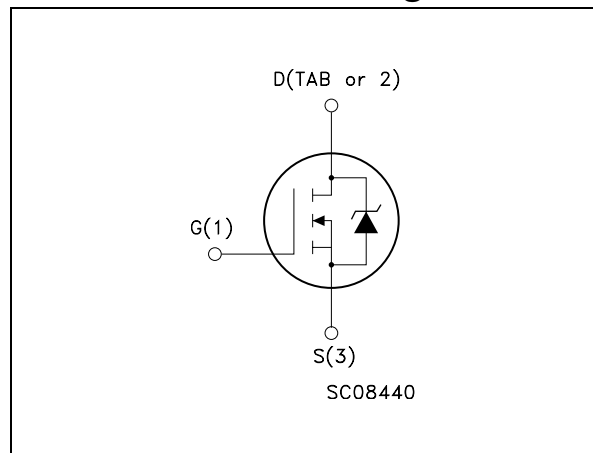
This Power MOSFET is the latest development of STMicroelectronics unique "Single Feature Size™" strip-based process. The resulting transistor shows extremely high packing density for low on-resistance, rugged avalanche characteristics and less critical alignment steps therefore a remarkable manufacturing reproducibility.

Applications

- Switching application



Internal schematic diagram



Order codes

| Part number | Marking | Package | Packaging |
|--------------|----------|---------|-------------|
| STD30NF03L-1 | D30NF03L | IPAK | Tube |
| STD30NF03LT4 | D30NF03L | DPAK | Tape & reel |

Contents

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1 Electrical ratings

Table 1. Absolute maximum ratings

| Symbol | Parameter | Value | Unit |
|----------------|---|------------|---------------------|
| V_{DS} | Drain-source voltage ($V_{GS} = 0$) | 30 | V |
| V_{DGR} | Drain-gate voltage ($R_{GS} = 20\text{ k}\Omega$) | 30 | V |
| V_{GS} | Gate- source voltage | ± 20 | V |
| $I_D^{(1)}$ | Drain current (continuous) at $T_C = 25^\circ\text{C}$ | 30 | A |
| I_D | Drain current (continuous) at $T_C = 100^\circ\text{C}$ | 19 | A |
| $I_{DM}^{(2)}$ | Drain current (pulsed) | 120 | A |
| P_{tot} | Total dissipation at $T_C = 25^\circ\text{C}$ | 50 | W |
| | Derating Factor | 0.27 | W/ $^\circ\text{C}$ |
| $E_{AS}^{(3)}$ | Single pulse avalanche energy | 100 | mJ |
| T_{stg} | Storage temperature | -65 to 175 | $^\circ\text{C}$ |
| T_j | Max. operating junction temperature | | |

1. Current limited by package
2. Pulse width limited by safe operating area.
3. Starting $T_j = 25^\circ\text{C}$, $I_D = 15\text{A}$ $V_{DD} = 15\text{V}$

Table 2. Thermal data

| | | | |
|----------------|--|-----|---------------------------|
| $R_{thj-pcb}$ | Thermal resistance junction-pcb max | 3.0 | $^\circ\text{C}/\text{W}$ |
| $R_{thj-amb}$ | Thermal resistance junction-ambient max | 100 | $^\circ\text{C}/\text{W}$ |
| $R_{thj-sink}$ | Thermal resistance case-sink max | 1.5 | $^\circ\text{C}/\text{W}$ |
| T_J | Maximum lead temperature for soldering purpose | 275 | $^\circ\text{C}$ |

2 Electrical characteristics

($T_{CASE}=25^{\circ}C$ unless otherwise specified)

Table 3. On/off states

| Symbol | Parameter | Test conditions | Min. | Typ. | Max. | Unit |
|---------------|--|---|------|----------------|----------------|----------------------|
| $V_{(BR)DSS}$ | Drain-source breakdown voltage | $I_D = 250\mu A, V_{GS} = 0$ | 30 | | | V |
| I_{DSS} | Zero gate voltage drain current ($V_{GS} = 0$) | $V_{DS} = \text{Max rating}$ $V_{DS} = \text{Max rating},$ $T_C = 125^{\circ}C$ | | | 1 10 | μA μA |
| I_{GSS} | Gate-body leakage current ($V_{DS} = 0$) | $V_{GS} = \pm 20V$ | | | ± 100 | nA |
| $V_{GS(th)}$ | Gate threshold voltage | $V_{DS} = V_{GS}, I_D = 250\mu A$ | 1 | 1.7 | 2.5 | V |
| $R_{DS(on)}$ | Static drain-source on resistance | $V_{GS} = 10V, I_D = 15A$ $V_{GS} = 4.5V, I_D = 15A$ | | 0.020 0.028 | 0.025 0.035 | Ω Ω |

Table 4. Dynamic

| Symbol | Parameter | Test conditions | Min. | Typ. | Max. | Unit |
|----------------|------------------------------|---|------|------|------|------|
| $g_{fs}^{(1)}$ | Forward transconductance | $V_{DS} = 15V, I_D = 15A$ | | 13 | | S |
| C_{iss} | Input capacitance | $V_{DS} = 25V, f = 1MHz,$ $V_{GS} = 0$ | | 830 | | pF |
| C_{oss} | Output capacitance | | | 230 | | pF |
| C_{rss} | Reverse transfer capacitance | | | 92 | | pF |
| $t_{d(on)}$ | Turn-on delay time | $V_{DD} = 15V, I_D = 20A$ $R_G = 4.7\Omega, V_{GS} = 4.5V$ (see Figure 12) | | 35 | | ns |
| t_r | Rise time | | | 205 | | ns |
| $t_{d(off)}$ | Turn-off delay time | | | 90 | | ns |
| t_f | Fall time | | | 240 | | ns |
| Q_g | Total gate charge | $V_{DD} = 24V, I_D = 30A,$ $V_{GS} = 5V, R_G = 4.7\Omega$ (see Figure 13) | | 18 | | nC |
| Q_{gs} | Gate-source charge | | | 7 | | nC |
| Q_{gd} | Gate-drain charge | | | 8 | | nC |

1. Pulsed: Pulse duration = 300 μs , duty cycle 1.5%.

Table 5. Source drain diode

| Symbol | Parameter | Test conditions | Min. | Typ. | Max. | Unit |
|-----------------------------------|--|--|------|---------------|-----------|---------------|
| I_{SD} $I_{SDM}^{(1)}$ | Source-drain current Source-drain current (pulsed) | | | | 30 240 | A A |
| $V_{SD}^{(2)}$ | Forward on voltage | $I_{SD} = 30A, V_{GS} = 0$ | | | 1.5 | V |
| t_{rr} Q_{rr} I_{RRM} | Reverse recovery time Reverse recovery charge Reverse recovery current | $I_{SD} = 40A, di/dt = 100A/\mu s,$ $V_{DD} = 15V, T_j = 150^\circ C$ (see Figure 14) | | 65 72 2 | | ns nC A |

1. Pulse width limited by safe operating area.
2. Pulsed: Pulse duration = 300 μs , duty cycle 1.5%

2.1 Electrical characteristics (curves)

Figure 1. Safe operating area

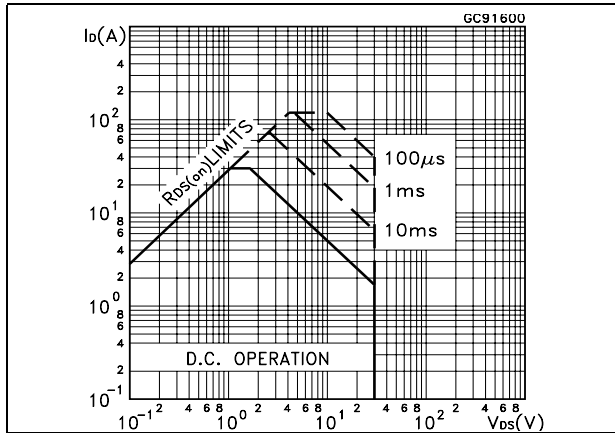


Figure 2. Thermal impedance

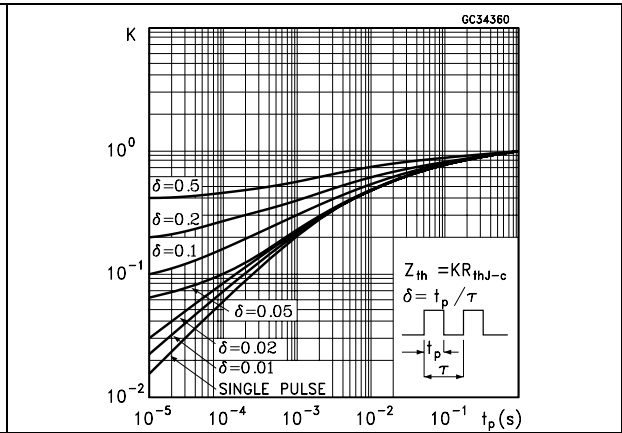


Figure 3. Output characteristics

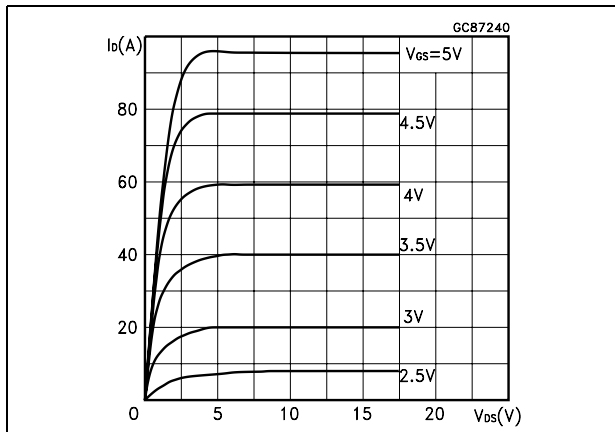


Figure 4. Transfer characteristics

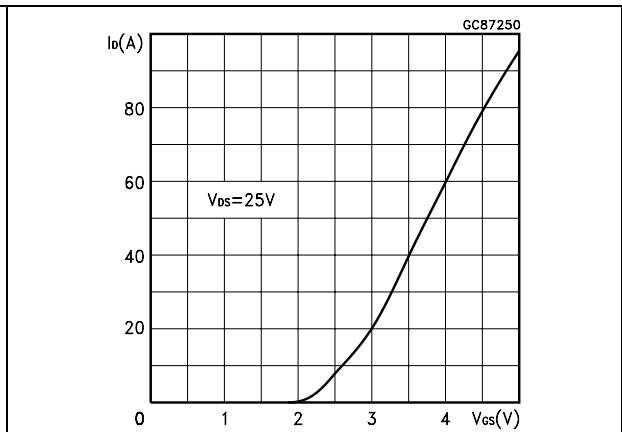


Figure 5. Transconductance

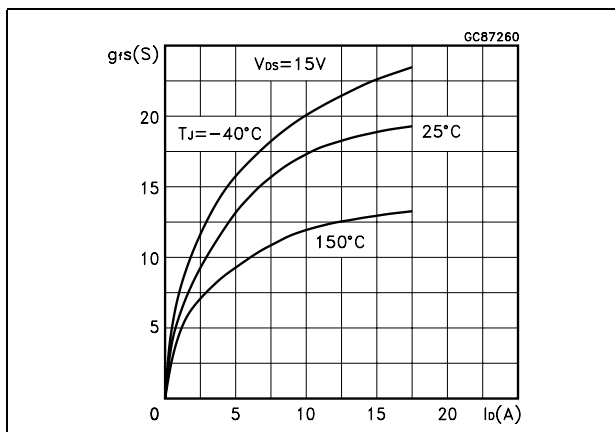


Figure 6. Static drain-source on resistance

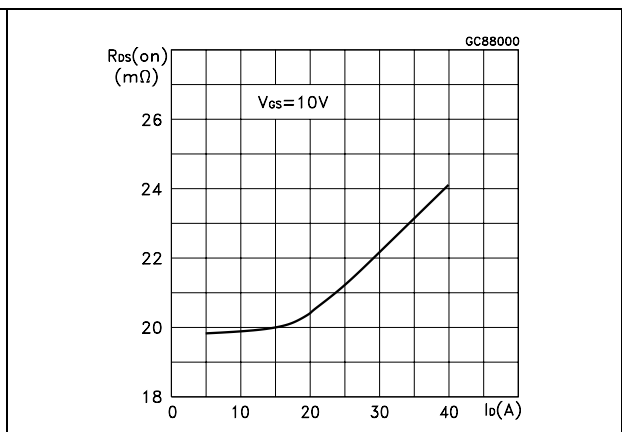


Figure 7. Gate charge vs. gate-source voltage Figure 8. Capacitance variations

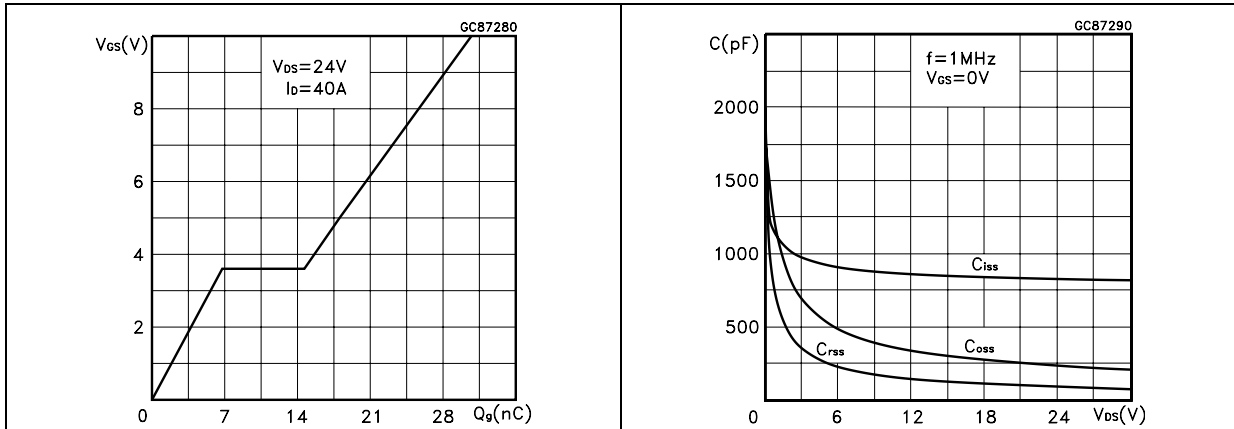


Figure 9. Normalized gate threshold voltage vs. temperature Figure 10. Normalized on resistance vs. temperature

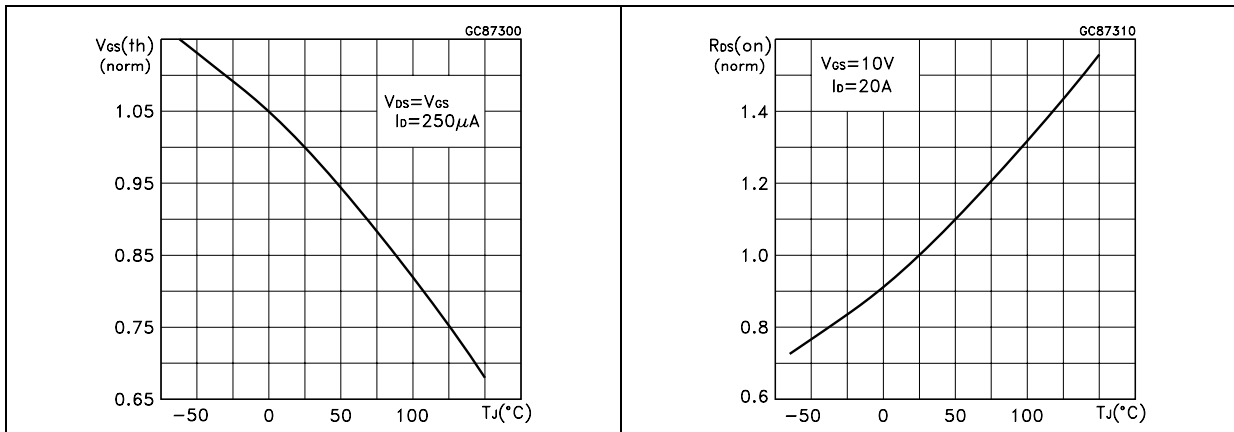
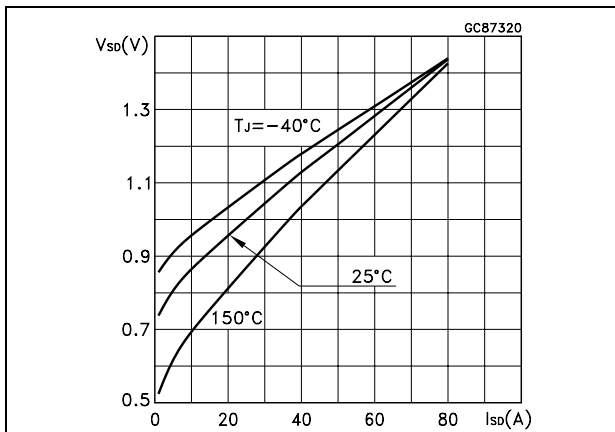


Figure 11. Source-drain diode forward characteristics



3 Test circuit

Figure 12. Switching times test circuit for resistive load



Figure 13. Gate charge test circuit



Figure 14. Test circuit for inductive load switching and diode recovery times



Figure 15. Unclamped Inductive load test circuit



Figure 16. Unclamped inductive waveform



Figure 17. Switching time waveform

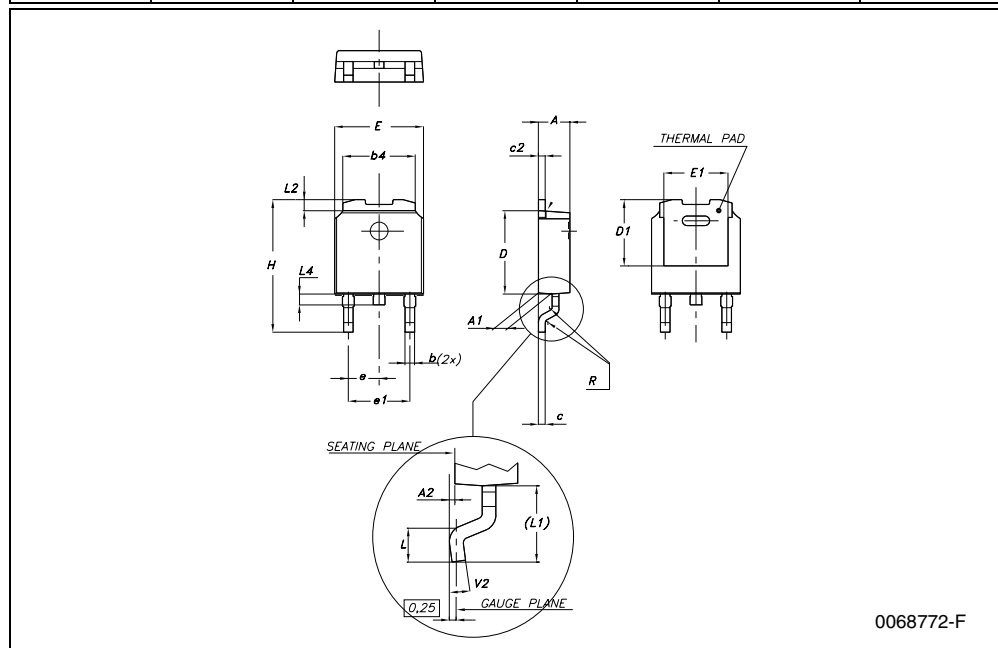


4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a Lead-free second level interconnect. The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com

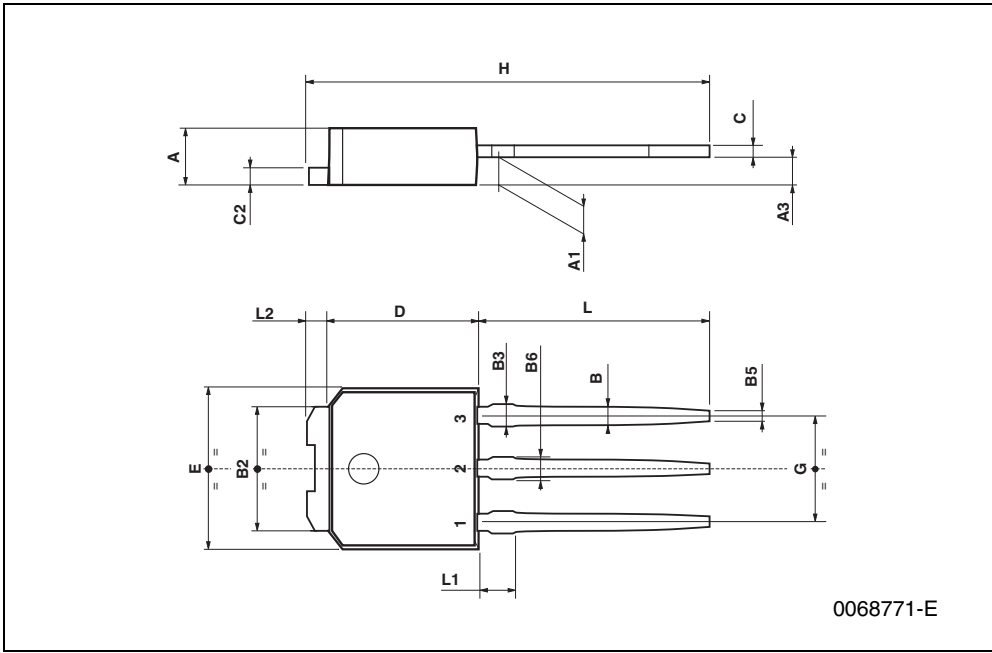
DPAK MECHANICAL DATA

| DIM. | mm. | | | inch | | |
|------|------|------|------|-------|-------|-------|
| | MIN. | TYP. | MAX. | MIN. | TYP. | MAX. |
| A | 2.2 | | 2.4 | 0.086 | | 0.094 |
| A1 | 0.9 | | 1.1 | 0.035 | | 0.043 |
| A2 | 0.03 | | 0.23 | 0.001 | | 0.009 |
| B | 0.64 | | 0.9 | 0.025 | | 0.035 |
| b4 | 5.2 | | 5.4 | 0.204 | | 0.212 |
| C | 0.45 | | 0.6 | 0.017 | | 0.023 |
| C2 | 0.48 | | 0.6 | 0.019 | | 0.023 |
| D | 6 | | 6.2 | 0.236 | | 0.244 |
| D1 | | 5.1 | | | 0.200 | |
| E | 6.4 | | 6.6 | 0.252 | | 0.260 |
| E1 | | 4.7 | | | 0.185 | |
| e | | 2.28 | | | 0.090 | |
| e1 | 4.4 | | 4.6 | 0.173 | | 0.181 |
| H | 9.35 | | 10.1 | 0.368 | | 0.397 |
| L | 1 | | | 0.039 | | |
| (L1) | | 2.8 | | | 0.110 | |
| L2 | | 0.8 | | | 0.031 | |
| L4 | 0.6 | | 1 | 0.023 | | 0.039 |
| R | | 0.2 | | | 0.008 | |
| V2 | 0° | | 8° | 0° | | 8° |



TO-251 (IPAK) MECHANICAL DATA

| DIM. | mm | | | inch | | |
|------|------|------|------|-------|-------|-------|
| | MIN. | TYP. | MAX. | MIN. | TYP. | MAX. |
| A | 2.2 | | 2.4 | 0.086 | | 0.094 |
| A1 | 0.9 | | 1.1 | 0.035 | | 0.043 |
| A3 | 0.7 | | 1.3 | 0.027 | | 0.051 |
| B | 0.64 | | 0.9 | 0.025 | | 0.031 |
| B2 | 5.2 | | 5.4 | 0.204 | | 0.212 |
| B3 | | | 0.85 | | | 0.033 |
| B5 | | 0.3 | | | 0.012 | |
| B6 | | | 0.95 | | | 0.037 |
| C | 0.45 | | 0.6 | 0.017 | | 0.023 |
| C2 | 0.48 | | 0.6 | 0.019 | | 0.023 |
| D | 6 | | 6.2 | 0.236 | | 0.244 |
| E | 6.4 | | 6.6 | 0.252 | | 0.260 |
| G | 4.4 | | 4.6 | 0.173 | | 0.181 |
| H | 15.9 | | 16.3 | 0.626 | | 0.641 |
| L | 9 | | 9.4 | 0.354 | | 0.370 |
| L1 | 0.8 | | 1.2 | 0.031 | | 0.047 |
| L2 | | 0.8 | 1 | | 0.031 | 0.039 |



5 Packing mechanical data

DPAK FOOTPRINT



TAPE AND REEL SHIPMENT

40 mm min. Access hole at slot location

Full radius

Tape slot in core for tape start 2.5mm min. width

G measured at hub

REEL MECHANICAL DATA

| DIM. | mm | | inch | |
|------|------|------|-------|--------|
| | MIN. | MAX. | MIN. | MAX. |
| A | | 330 | | 12.992 |
| B | 1.5 | | 0.059 | |
| C | 12.8 | 13.2 | 0.504 | 0.520 |
| D | 20.2 | | 0.795 | |
| G | 16.4 | 18.4 | 0.645 | 0.724 |
| N | 50 | | 1.968 | |
| T | | 22.4 | | 0.881 |

TAPE MECHANICAL DATA

| DIM. | mm | | inch | |
|------|------|------|-------|-------|
| | MIN. | MAX. | MIN. | MAX. |
| A0 | 6.8 | 7 | 0.267 | 0.275 |
| B0 | 10.4 | 10.6 | 0.409 | 0.417 |
| B1 | | 12.1 | | 0.476 |
| D | 1.5 | 1.6 | 0.059 | 0.063 |
| D1 | 1.5 | | 0.059 | |
| E | 1.65 | 1.85 | 0.065 | 0.073 |
| F | 7.4 | 7.6 | 0.291 | 0.299 |
| K0 | 2.55 | 2.75 | 0.100 | 0.108 |
| P0 | 3.9 | 4.1 | 0.153 | 0.161 |
| P1 | 7.9 | 8.1 | 0.311 | 0.319 |
| P2 | 1.9 | 2.1 | 0.075 | 0.082 |
| R | 40 | | 1.574 | |
| W | 15.7 | 16.3 | 0.618 | 0.641 |

TOP COVER TAPE

User Direction of Feed

Center line of cavity

Bending radius R min.

FEED DIRECTION

TRL

For machine ref. only including draft and radii concentric around B0

10 pitches cumulative tolerance on tape +/- 0.2 mm

6 Revision history

Table 6. Revision history

| Date | Revision | Changes |
|-------------|-----------------|---------------------------------|
| 21-Jun-2004 | 4 | Preliminary version |
| 03-Jul-2006 | 5 | New template, no content change |
| 20-Feb-2007 | 6 | Typo mistake on page 1 |

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